

BB02-RG :-2.0mm x 2.0mm (0.079" x 0.79") SOCKET, STRAIGHT, SMD, DUAL ROW - 04 to 80 CONTACTS LOW PROFILE:2.2mm, DUAL ENTRY

SPECIFICATIONS

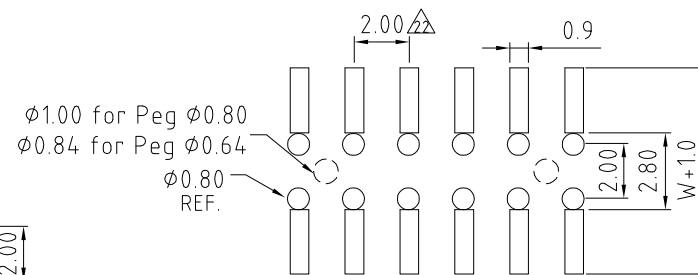
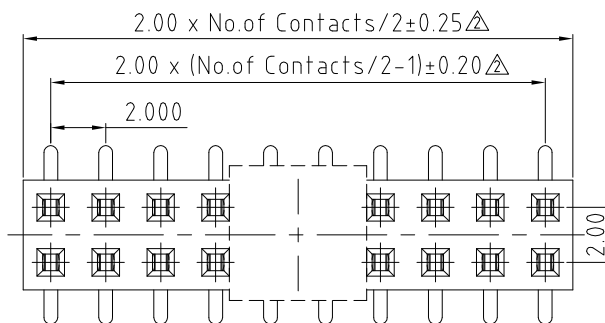
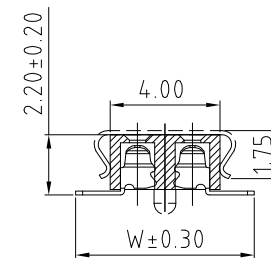
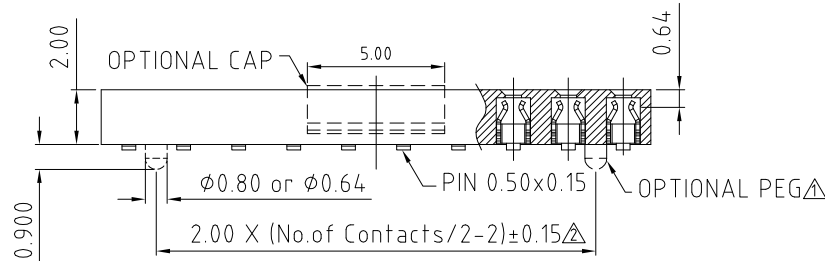
CURRENT RATING	2 AMP
INSULATOR RESISTANCE	1000 MEGOHMS MIN.
CONTACT RESISTANCE	20m ohms MAX.
DIELECTRIC WITHSTANDING	AC 500 V
OPERATING TEMPREATURE	-40°C TO +105°C
CONTACT MATERIAL	PHOSPHOR BRONZE
INSULATOR MATERIAL	THERMOPLASTIC, UL 94V-0 STANDARD: NYLON 6T
PLATING	GOLD OR TIN OVER 30-50U" NICKEL
SOLDERABILITY	IR REFLOW: 260°C FOR 10 SEC MANUAL SOLDER: 350°C FOR 3-5 SEC

NOTES:

1. RECOMMENDED MATING PIN LENGTH FOR TOP ENTRY: 1.5MM. Δ
2. PARTS WITH SMALLER NUMBER OF CONTACTS MIGHT BE PACKED IN BOX INSTEAD OF IN TUBE.

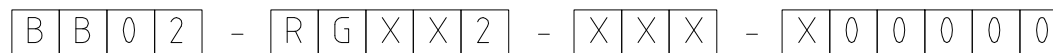
MATES WITH:

BB02-FA	BB02-FZ
BB02-FD	BB02-RH
BB02-FE	BB02-RN
BB02-FG	BB02-2F
BB02-FU	BB02-4F



BOTTOM ENTRY TYPE
RECOMMENDED PC BOARD LAYOUT
(TOLERANCE:±0.05)

HOW TO ORDER



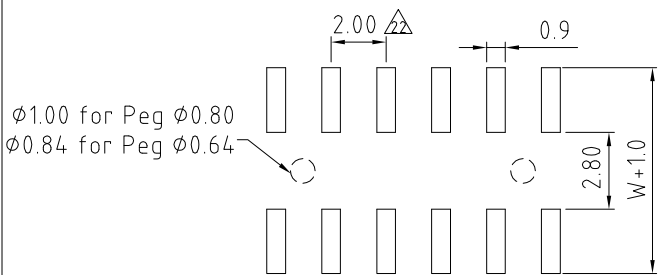
NO. OF CONTACTS:
 Δ 04 TO 80
(MIN. 06 FOR W/PEG)

Δ FOOTPRINT
"W" OPTIONS:
0 = 6.5MM
A = 5.3MM
 Δ B = 6.1MM

PACKAGING OPTIONS:
3 = TUBE
 Δ 4 = TUBE + FILM
5 = TUBE + CAP
6 = TAPE & REEL
 Δ 7 = TAPE & REEL + FILM
8 = TAPE & REEL + CAP
(see note 2)

Δ LOCATING PEG OPTIONS:
A = WITH PEG ϕ 0.80 (W=6.5 OR 5.3)
B = WITHOUT PEG
 Δ C = WITH PEG ϕ 0.64 (W=5.3 OR 6.1)

$\Delta\Delta\Delta$ CONTACT PLATING OPTIONS:
K = GOLD FLASH (STANDARD)
A = 10U" GOLD ON CONTACT/GOLD FLASH ON TAIL
B = 15U" GOLD ON CONTACT/GOLD FLASH ON TAIL
C = 30U" GOLD ON CONTACT/GOLD FLASH ON TAIL
T = BRIGHT TIN
M = MATT TIN



TOP ENTRY TYPE
RECOMMENDED PC BOARD LAYOUT
 Δ (TOLERANCE:±0.05)

REV. DATE & DRN	10. 12/05/05 - NYW RELEASE
11. 3/06/07 - NYW	11. ADD PEG OPTION 4 & 7.
12. 06/06/06 - NYW	12. MIN. CONTACT NO 06=04.
13. 08/08/06 - NYW	13. AMEND DIMENSIONS.
14. 02/10/06 - CHC	14. DRAWING MODIFICATION.
15. 31/05/07 - NYW	15. REMOVE SELECTIVE GOLD.
16. 25/07/07 - CHC	16. ADD FOOTPRINT W OPTION.
17. 16/10/07 - CHC	17. ADD SELECTIVE GOLD.
18. 08/07/08 - NYW	18. REMOVE SELECTIVE GOLD CONTACT PLATING.
19. 04/03/08 - CHC	19. CONTACT PLATING MODIFICATION.
20. 10/03/08 - CHC	20. ADD PEG OPTION C.
21. 31/12/08 - NYW	21. ADD TOLERANCE OF PCB LAYOUT.
22. 23/03/10 - NYW	22. DRAWING MODIFICATION.
23. 04/05/12 - NYW	23. AMEND PCB LAYOUT.
24. 30/10/13 - NYW	24. ADD FOOTPRINT OPTION B.
25. 07/03/14 - NYW	25. ADD NOTE 2.
	25. AMEND MATING P/N.

Scale: 5:1	THIRD ANGLE	Unstated Tolerances: X ± 0.30 X ± 0.25 XX ± 0.15 .XXX ± 0.10	Material SEE NOTE
Drawn: CHC			
App'd: XXXX	Title: SOCKET		NOT TO SCALE
Date: 7 MAR. '14	Revision: 2.5		Unit: mm

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Type: BB02-RG
BB02-RG
Drawing Number:
Sheet 1 of 1
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